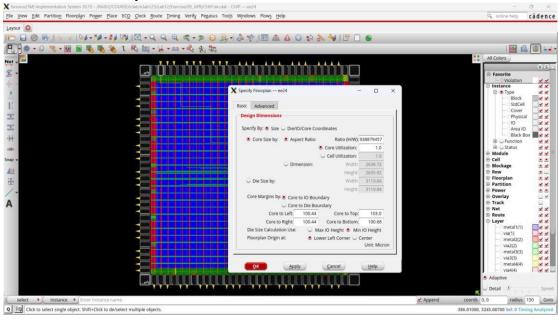
ICLAB LAB12 Report

國際半導體學院碩一

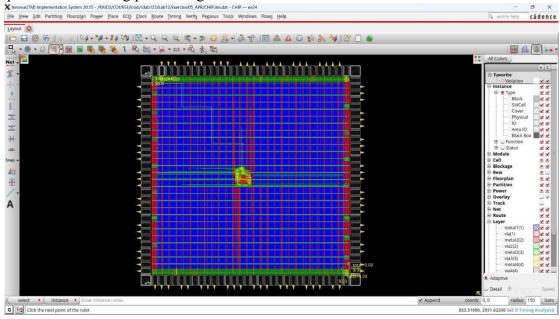
ICLAB 帳號: iclab125 學號: 313591021 姓名:沈佳瞳

1.Core to IO boundary

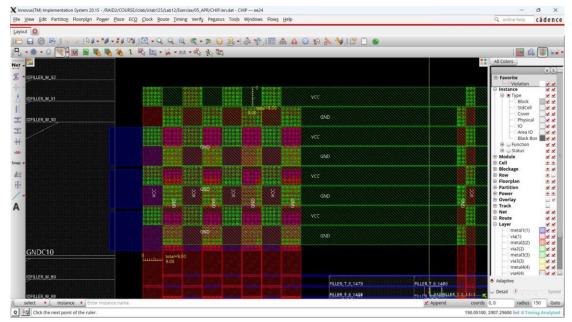


2.Core Ring

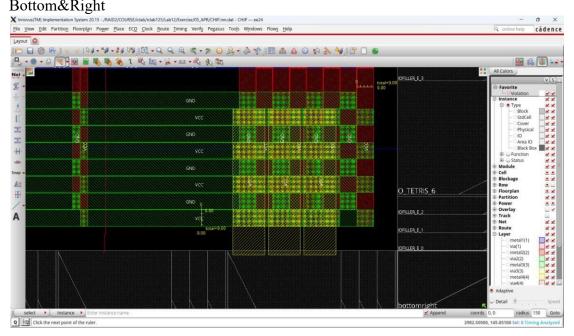
4pairs &interleaving power ring



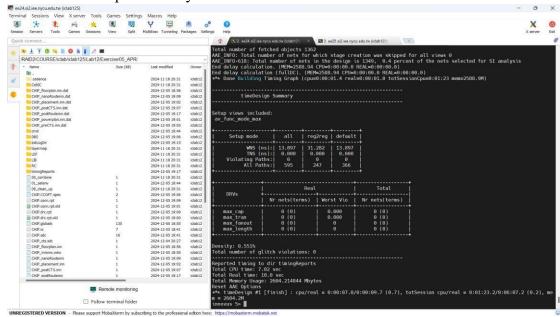
Top&Left



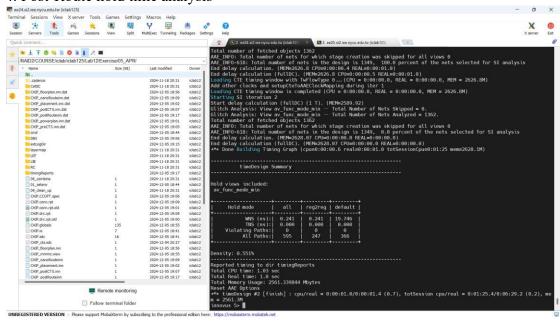




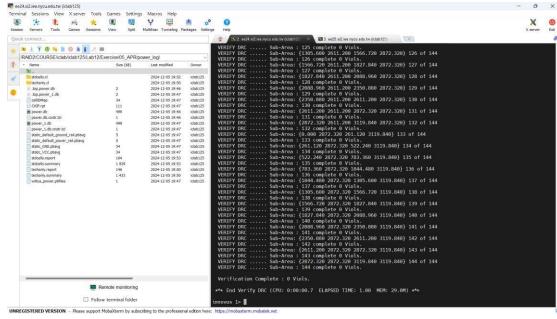
3.Post-Route setup time analysis



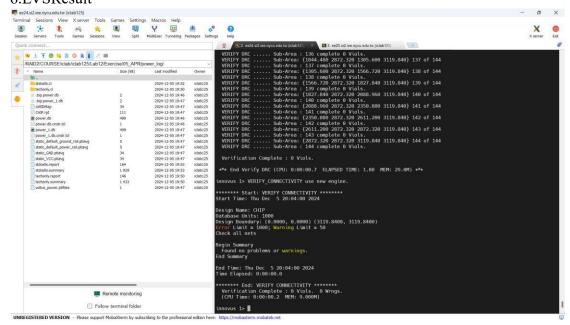
4. Post-Route hold time analysis



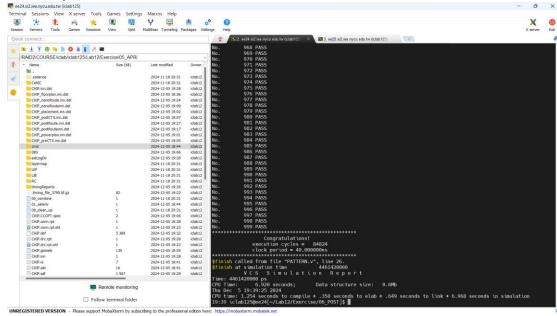
5.DRC result



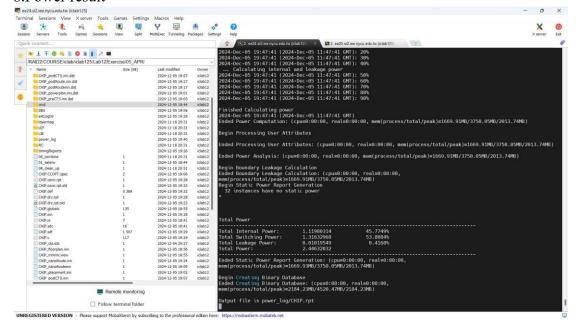
6.LVSResult



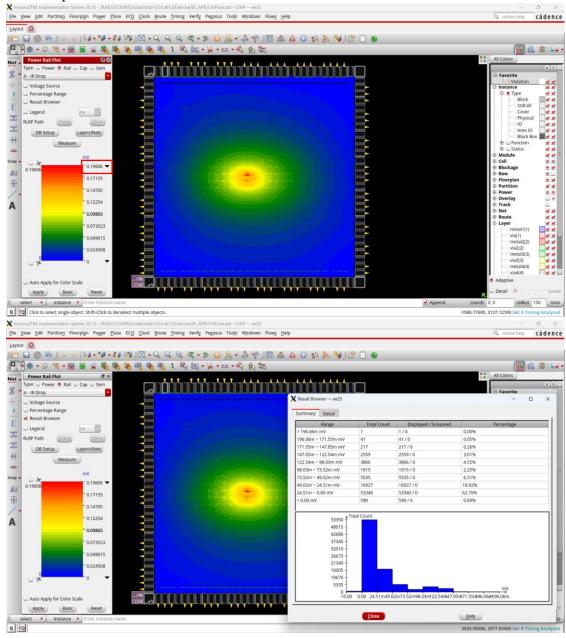
7.Post Layout simulation result



8. Power result



9.IR Drop result



降低 IR drop 的方法:

IR drop 是指電流流經步線網路造成的電壓損耗。我將 chip 設計為正方形,放置了 12 組 core power pads,平均分布在 chip 的四個邊,避免 power 走線過長。 最終 IR drop 小於 0.2 mV。